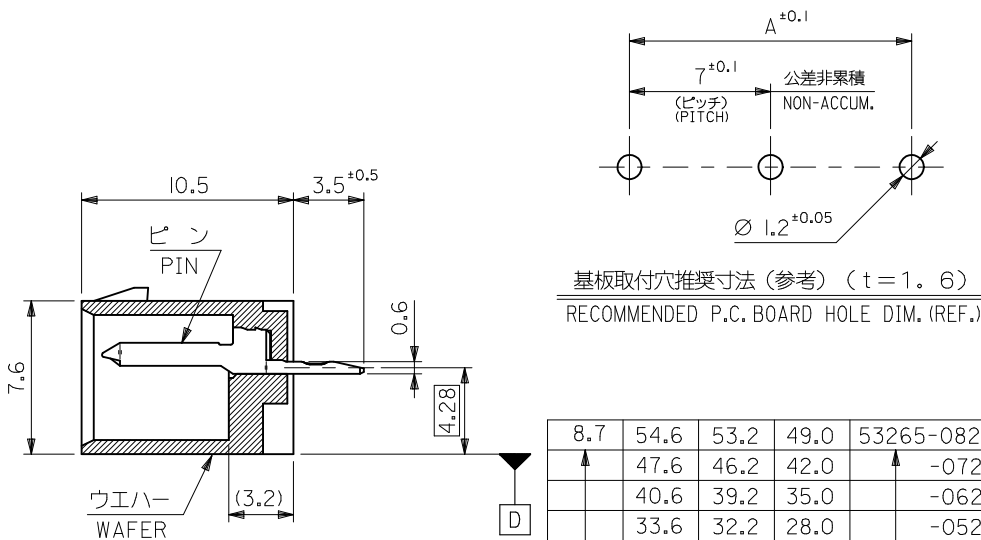


注記 NOTES

1. 嵌合相手 : 51067 シリーズ  
MATE WITH : 51067 SERIES
2. 材質  
MATERIAL  
ウエハー : PBTP (ガラス15%入り)、UL94V-0  
WAFER : PBTP (G.F 15%), UL94V-0  
ピン : 黄銅、ニッケル下地 錫メッキ (t=0.254)  
PIN : BRASS, TIN OVER NICKEL PLATING (t=0.254)
3. 本製品は 53265-\*\*20 の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 53265-\*\*20.



8.7	54.6	53.2	49.0	53265-0829	8
↑	47.6	46.2	42.0	↑ -0729	7
	40.6	39.2	35.0	↑ -0629	6
	33.6	32.2	28.0	↑ -0529	5
↓	26.6	25.2	21.0	↑ -0429	4
8.7	19.6	18.2	14.0	↓ -0329	3
6.1	12.6	11.2	7.0	53265-0229	2
(D)	C	B	A	TRAY PACKAGE	CKT. 極数
				ORDER No. オート番号	

REVISED EC NO: J2009-1054 DRWN: MABEI 2009/02/17 CHKD: HYAJIMA 2009/02/18 APPR: NUKITA 2009/02/18 REV A	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---		MODEL NO. DESIGN UNITS METRIC		THIRD ANGLE PROJECTION		
	10 UNDER	±0.2	DRAWN BY	DATE	TITLE						
	10 OVER 30 UNDER	±0.25	Y. WADA	'04/04/22	7.0 WIRE TO BOARD CONN. WAFER ASS'Y (ST.) -LEAD FREE-						
	30 OVER	±0.3	CHECKED BY	DATE	MOLEX MOLEX INCORPORATED						
	ANGULAR	±3 °	M. SASAO	'04/04/22	DOCUMENT NO. SD-53265-005 SHEET NO. 1 OF 1						
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY M. SASAO '04/04/22		MATERIAL NO. SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					